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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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10/560,717

12/15/2005

Freddy Roozeboom

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11/23/2007

NXP, B.V.

NXP INTELLECTUAL PROPERTY DEPARTMENT

M/S41-SJ

1109 MCKAY DRIVE

SAN JOSE, CA 95131

EXAMINER

PHINAZEE, SIDNEY S

ART UNIT

PAPER NUMBER

4122

NOTIFICATION DATE

DELIVERY MODE

11/23/2007

ELECTRONIC

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

ip.department.us@nxp.com

<b>Office Action Summary</b>	<b>Application No.</b> 10/560,717	<b>Applicant(s)</b> ROOZEBOOM ET AL.	
	<b>Examiner</b> Sidney S. Phinazee	<b>Art Unit</b> 4122	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 23 October 2007.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 1-10 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-10 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☒ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 15 December 2005 is/are: a) ☐ accepted or b) ☒ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All    b) ☐ Some \*    c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- \* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)            | 4) <input type="checkbox"/> Interview Summary (PTO-413)           |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)   | Paper No(s)/Mail Date. _____                                      |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date <u>8-29-06</u> .   | 6) <input type="checkbox"/> Other: _____                          |

## **DETAILED ACTION**

### ***Election/Restrictions***

1. Applicant's election without traverse of group I (claims 1-10) in the reply filed on October 23,2007 is acknowledged.

### ***Drawings***

2. The drawings are objected to as failing to comply with 37 CFR 1.84(p)(5) because they include the following reference character(s) not mentioned in the description: Fig 2d reference (43). Corrected drawing sheets in compliance with 37 CFR 1.121(d), or amendment to the specification to add the reference character(s) in the description in compliance with 37 CFR 1.121(b) are required in reply to the Office action to avoid abandonment of the application. Any amended replacement drawing sheet should include all of the figures appearing on the immediate prior version of the sheet, even if only one figure is being amended. Each drawing sheet submitted after the filing date of an application must be labeled in the top margin as either "Replacement Sheet" or "New Sheet" pursuant to 37 CFR 1.121(d). If the changes are not accepted by the examiner, the applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance.

### ***Specification***

1. The disclosure is objected to because of the following informalities: (page 11 line 34) the first conductive surface was referenced, as 23 and might have meant to reference as 22. Further in the disclosure (page 15 lines 16 and 17) discuss lead frame

referenced as 210 and might have meant to refer it as 310. Appropriate correction is required.

### ***Claim Objections***

2. Claim 6 is objected to because of the following informalities: which Claim 6 recites the limitation “ the first and second vertical interconnect are designed so as to form a coaxial structure”. There is insufficient antecedent basis for this limitation in the claim. Additionally it appears this claim should depend upon claim 5, which recites the first and second interconnect. Appropriate correction is required.

### ***Claim Rejections - 35 USC § 103***

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 1, 3, 5, 7-8, and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chudzik et al (7,030,481) in view of Larson et al (5,495,117).

5. Regarding claim 1 Chudzik discloses an electronic device comprising a semiconductor substrate (200) having a first and a second side and provided with a capacitor and a vertical interconnect (210, 410', 610') through the substrate (200) extending from the first to the second side, on which first side the capacitor is present, characterized in that the capacitor is a vertical trench capacitor (3010) provided with a plurality of trenches in which a layer of dielectric material is present between a first (3030) and a second (3080) conductive surface (See Fig 3b, 4b, and 6). Chudzik does

not disclose the layer of dielectric material being used as insulation between the substrate and the vertical interconnect. However Larson discloses the layer of dielectric material being used as insulation between the substrate and the vertical interconnect (Larson reference 20, 26, 36). It would have been obvious to one having ordinary skill in the art at the time of the invention to incorporate the teachings of Larson into Chudzik because it is well known in the art that using dielectric material to isolate conductors from one another allows for safe current without arcing.

6. Regarding claim 3 which includes the limitations of claim 1 (addressed above), Chudzik discloses an electronic device, characterized in that the trenches of the vertical interconnect are substantially filled with electrically conductive material (230,430).

7. Regarding claim 5 Chudzik discloses an electronic device, characterizes contact pads (240, 270) being present. Chudzik does not explicitly state that the contact pads are for coupling to an external carrier that is present on the second side; or that a first vertical interconnect is used for grounding or that a second interconnect is used for signal transmission.

8. A recitation of the intended use of the claimed invention must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior structure is capable of performing the intended use, then it meets the claim. The applicants intended use of the claimed structure does not structurally distinguish itself over the structure taught by Chudzik. Therefore the recitation of the "a first vertical interconnect

is used for grounding” and “second interconnect is used for signal transmission” has not been given patentable weight.

9. Regarding claim 7 Chudzik discloses an electronic device characterized in that an integrated circuit is defined on the second side of the substrate (See Chudzik column 7 lines 57-60).

10. Regarding claim 8, which includes all the limitations of claim 1 (addressed above) Chudzik discloses the substrate to comprise a high ohmic zone (Spec column 5 lines 34-37), which is adjacent to the vertical capacitors and acts as a protection against parasitic currents. (See Fig 3C)

11. Regarding claim 10, which includes all the limitations of claim 1 (addressed above) Chudzik discloses an assembly comprising the electronic device, and a semiconductor device, which semiconductor device (102) is electrically connected to bond pads (270) present on the first side of the substrate.

12. Claims 2,4, and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chudzik (7,030,481) in view of Larson (5,495,117), as applied to claim 1 above, and further in view of Kosaki et al (6,268,619).

13. Regarding claim 2 Chudzik and Larson disclose the limitations of claim 1 but neither reference discloses the limitations of claim 2 of the vertical interconnect, which first part is exposed on the first side of the substrate, is narrower than the second part

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and has a substantially cylindrical shape. However, Kosaki discloses the vertical interconnect which first part is exposed on the first side of the substrate, is narrower than the second part and has a substantially cylindrical shape (3) (see figure 14). It would have been obvious to one having ordinary skill in the art at the time the invention to incorporate the teaching of Kosaki with that of Chudzik and Larson because in this sixth embodiment, the anisotropic dry etching as well as the wet isotropic etching form the opening (3). Therefore, in the vicinity of the front surface of the substrate, the opening has a cylindrical shape so that the substrate is not locally thin, thereby suppressing occurrence of cracks. (See Kosaki column 17 lines 10-15)

14. Regarding to claim 4 which include limitations of claim 2 (addressed above) Chudzik discloses an electronic device, characterized in that the vertical interconnect comprises a plurality of parallel through-holes through the substrate, each of which is filled with electrically conductive material (230, 430).

15. Regarding claim 6, which includes limitations of claim 4 (addressed above) Chudzik discloses an electronic device that is characterized in that the first (210) and second (610) interconnect are designed so as to form a coaxial structure.

16. Claim 9 is rejected under 35 U.S.C. 103(a) as being unpatentable over Chudzik (7,030,481) in view of Larson (5,495,117), as applied to claim 1 above, and further in view of Goldberger et al (6,538,300).

17. Regarding claim 9 Chudzik and Larson disclose all of the limitations of claim 1 but neither reference discloses all limitations of claim 9 that characterizes a planar capacitor that is present on the first side of the substrate, which planar capacitor comprises the same layer of dielectric material as the vertical capacitor. However, Goldberger discloses an electronic device, characterized in that a planar capacitor is present on the first side of the substrate, which planar capacitor (10) comprises the same layer of dielectric material (104) as the vertical capacitor. It would have been obvious to one having ordinary skill in the art at the time the invention to incorporate the teaching of Goldberger with that of Chudzik and Larson because capacitors in accordance with Goldberger's invention exhibit numerous advantages. For example, they can be fabricated at a wafer level with a very low effective series resistance (ESR). (See Goldberger column 1 paragraph 8).

### ***Conclusion***

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Sidney S. Phinazee whose telephone number is (571) 270-5020. The examiner can normally be reached on Monday-Friday 7:30am-5:00pm est.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Mark Robinson can be reached on (571) 272-2319. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.



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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

SSP

/Mark A. Robinson/

Supervisory Patent Examiner, Art Unit 4122

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